



SOT1311-1

Plastic small outline package; 8 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	18-8-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.08	-	5.28	5.48	mm
E	package width		5.08	-	5.28	5.48	mm
A	seated height		[tbd]	-	[tbd]	2.16	mm
A ₂	package height		1.7	-	1.91	1.8	mm
e	nominal pitch		-	-	1.27	-	mm
n ₂	actual quantity of termination		-	-	8	-	

2. Package outline

Fig. 1. Package outline SO8 (SOT1311-1)



3. Legal information

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